

Product / Process Change Notification



N° 2019-182-A

Dear Customer,

please find attached our INFINEON Technologies PCN:

Several changes for Gen 7N MOSFETs affecting D2PAK, DPAK and TO220 packages

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2021-01-31.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates:
"Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."
Notwithstanding the aforesaid individual agreements shall prevail.

Your prompt reply will help Infineon Technologies to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
Postal Address Headquarters: Am Campeon 1-15, D-85579 Neubiberg, Phone +49 (0)89 234-0
Chairman of the Supervisory Board: Dr. Wolfgang Eder
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider
Registered Office: Neubiberg
Commercial Register: München HRB 126492

Product / Process Change Notification



N° 2019-182-A

Products affected

Please refer to attached affected product list 1_cip19182_A

Detailed Change Information

Subject:

Several changes for Gen 7N MOSFETs affecting D2PAK, DPAK and TO220 packages

Reason / Motivation:

Production Consolidation

Description	Old	New
PROCESS - WAFER PRODUCTION: New / change of metallization (specifically chip backside)	Cr/Ni/Ag Sputter	Ti/Ni/Ag Evap
PROCESS - WAFER PRODUCTION: New / change of metallization (specifically chip frontside)	Al/Si	Al/Si/Cu
PROCESS - WAFER PRODUCTION: Move of all or part of wafer fab to a different location/site/subcontractor	Infineon Technologies Americas Corp., Temecula, United States	EPISIL Taiwan
PROCESS - ASSEMBLY: Change of lead frame finishing material / area (internal)	Ni plated in all area except die pad;	Cu in all area except on T-post ;
PROCESS - ASSEMBLY: Change of product marking	No Site code	Site Code M
PROCESS - ASSEMBLY: Move of all or part of assembly to a different location/site/subcontractor.	Rectificadores Internacionales, S.A. de C.V., Tijuana , Mexico	Rectificadores Internacionales, S.A. de C.V., Tijuana , Mexico and Tongfu Microelectronics Co., Ltd
TEST FLOW: Move of all or part of electrical wafer test and/or final test to a different location/site/subcontractor	Wafer Probe site: Infineon Technologies Americas Corp., Temecula, United States Final test: Rectificadores Internacionales, S.A. de C.V., Tijuana , Mexico	Wafer Probe site: EPISIL Taiwan Final test: Rectificadores Internacionales, S.A. de C.V., Tijuana , Mexico and Tongfu Microelectronics Co., Ltd

Product / Process Change Notification



N° 2019-182-A

Product Identification

Traceability assured via Lot number and date code.

Anticipated Impact of Change

No expected impact on electrical performance expected. Quality and reliability verified by qualification. There is no change in form, fit and function.

Attachments

1_cip19182_A	affected product list
--------------	-----------------------

Time Schedule

Final qualification report	2020-09-09
First samples available	2020-09-09
Intended start of delivery [1]	2021-06-30
Last Delivery Date (LDD) [3]	2021-10-31

If you have any questions, please do not hesitate to contact your local Sales Office.

PCN N° 2019-182-A

Several changes for Gen 7N MOSFETs affecting D2PAK, DPAK and TO220 packages



Sales name	SP number	OPN	Package
AUIRF1404	SP001522606	AUIRF1404	PG-TO220-3-904
AUIRF1404S	SP001522616	AUIRF1404S	PG-TO263-3-901
AUIRF1404STRL	SP001517298	AUIRF1404STRL	PG-TO263-3-901
AUIRF3205	SP001519502	AUIRF3205	PG-TO220-3-904
AUIRFR2407TRL	SP001520552	AUIRFR2407TRL	PG-TO252-3-901
AUIRFZ48N	SP001518286	AUIRFZ48N	PG-TO220-3-904